

REMARKS

The above amendments to the above-captioned application along with the following remarks are being submitted as a full and complete response to the Official Action dated November 3, 2004. In view of the above amendments and the following remarks, the Examiner is respectfully requested to give due consideration to this application, to indicate the allowability of the claims, and to pass this case to issue.

Status of the Claims

Claims 1-5 and 21-22 are under consideration in this application. Claims 1 and 5 are being amended, as set forth in the above marked-up presentation of the claim amendments, in order to more particularly define and distinctly claim applicant's invention. New claims 6-7 are being added to recite the embodiments described in the specification.

The claims are being amended to correct formal errors and/or to better recite or describe the features of the present invention as claimed. All the amendments to the claims are supported by the specification. Applicant hereby submits that no new matter is being introduced into the application through the submission of this response.

Prior Art Rejections

Claims 1-5 were rejected under 35 U.S.C. § 102(b) on the grounds of being anticipated by US Pat. No. 5,923,047 to Chia et al. (hereinafter "Chia"). The prior art reference of Chiu (US Pat. No. 5,532,614) and Gu et al. (US Pat. No. 6,759,865) were cited as being pertinent to the present application. These rejections have been carefully considered, but are most respectfully traversed.

The semiconductor integrated circuit device of the invention (e.g., Fig. 1), as now recited in claim 1, comprises: a plurality of bonding pads 311, 312, 313, etc. arranged along one of four sides (e.g., the left side) of at least one semiconductor chip embedded in the semiconductor integrated circuit device 1; at least one inspection pad 211 on another one of the four sides (e.g., the upper side) of the semiconductor chip; and a corresponding connection wire 411, which is laid outside an input/output buffer area 3 of the chip for each of said bonding pads, for connecting said each bonding pad 311 with the inspection pad 211.

Applicants respectfully contend that none of the cited prior art references teaches or suggests "a bonding pad and an inspection pad wired with the bonding pad placed on *different* ones of the four sides of a semiconductor chip" as does the invention.

As a result, bonding pads can be along one side or two opposite sides of the chip rather than the four sides of the chip (p. 4, last two lines) such that the invention can use easy-to-produce and inexpensive probe cards to inspect a plurality of semiconductor integrated circuit devices at a time (p. 4, lines 19-21).

In contrast, Chia (Fig. 2) only has a bonding pad 14 and an inspection pad 20 wired with the bonding pad placed on the *same*/bottom (rather than “different”) one of the four sides of a semiconductor chip 12C. It is well established that a rejection based on cited references having that teach away from the invention is improper.

The other cited references fail to compensate for Chia’s deficiencies.

None of the cited references teaches or suggests each and every feature of the present invention as recited in independent claim 1. As such, the present invention as now claimed is distinguishable and thereby allowable over the rejections raised in the Office Action. The withdrawal of the outstanding prior art rejections is in order, and is respectfully solicited.

Conclusion

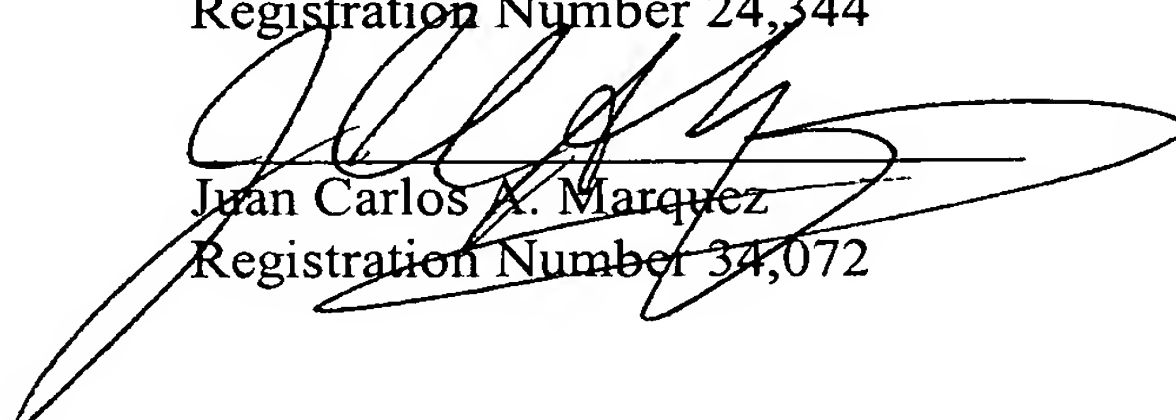
In view of all the above, Applicants respectfully submit that certain clear and distinct differences as discussed exist between the present invention as now claimed and the prior art references upon which the rejections in the Office Action rely. These differences are more than sufficient that the present invention as now claimed would not have been anticipated nor rendered obvious given the prior art. Rather, the present invention as a whole is distinguishable, and thereby allowable over the prior art.

Favorable reconsideration of this application as amended is respectfully solicited. Should there be any outstanding issues requiring discussion that would further the prosecution and

allowance of the above-captioned application, the Examiner is invited to contact the Applicant's undersigned representative at the address and phone number indicated below.

Respectfully submitted,

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